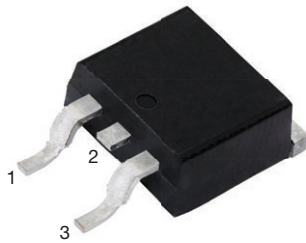
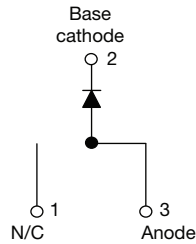


High Performance Schottky Rectifier, 8 A


D²PAK (TO-263AB)


FEATURES

- 175 °C T_J operation
- Low forward voltage drop
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


**RoHS
COMPLIANT
HALOGEN
FREE**

PRIMARY CHARACTERISTICS

I _{F(AV)}	8 A
V _R	80 V, 100 V
V _F at I _F	0.58 V
I _{RM}	7 mA at 125 °C
T _J max.	175 °C
E _{AS}	7.5 mJ
Package	D ² PAK (TO-263AB)
Circuit configuration	Single

DESCRIPTION

The VS-8TQ... Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
I _{F(AV)}	Rectangular waveform	8	A
V _{RRM}	Range	80/100	V
I _{FSM}	t _p = 5 μs sine	850	A
V _F	8 A _{pk} , T _J = 125 °C	0.58	V
T _J	Range	-55 to +175	°C

VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-8TQ080S-M3	VS-8TQ100S-M3	UNITS
Maximum DC reverse voltage	V _R	80	100	V
Maximum working peak reverse voltage	V _{RWM}			

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current See fig. 5	I _{F(AV)}	50 % duty cycle at T _C = 157 °C, rectangular waveform	8	A
Maximum peak one cycle non-repetitive surge current See fig. 7	I _{FSM}	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated V _{RRM} applied	850
		10 ms sine or 6 ms rect. pulse		230
Non-repetitive avalanche energy	E _{AS}	T _J = 25 °C, I _{AS} = 0.50 A, L = 60 mH	7.50	mJ
Repetitive avalanche current	I _{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T _J maximum V _A = 1.5 x V _R typical	0.50	A



ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	$V_{FM}^{(1)}$	8 A	$T_J = 25\text{ }^\circ\text{C}$	0.72	V
		16 A		0.88	
		8 A	$T_J = 125\text{ }^\circ\text{C}$	0.58	
		16 A		0.69	
Maximum reverse leakage current See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	0.55	mA
		$T_J = 125\text{ }^\circ\text{C}$		7	
Maximum junction capacitance	C_T	$V_R = 5\text{ }V_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^\circ\text{C}$		500	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		8	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/ μ s

Note

(1) Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}			-55 to +175	$^\circ\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation See fig. 4		2.0	$^\circ\text{C}/\text{W}$
Typical thermal resistance, case to heatsink	R_{thCS}	Mounting surface, smooth, and greased		0.50	
Approximate weight				2	g
				0.07	oz.
Mounting torque	minimum			6 (5)	kgf · cm (lb · in)
	maximum			12 (10)	
Marking device		Case style D ² PAK (TO-263AB)		8TQ080S	
				8TQ100S	

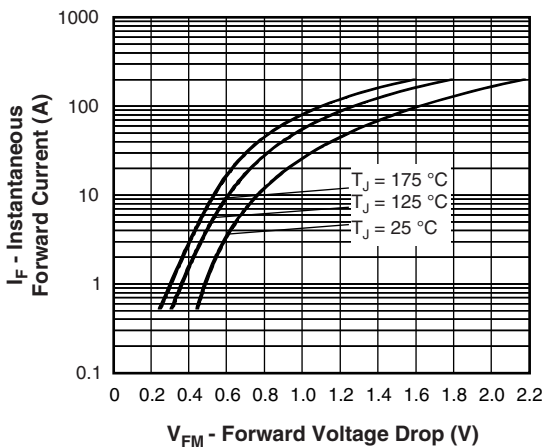


Fig. 1 - Maximum Forward Voltage Drop Characteristics

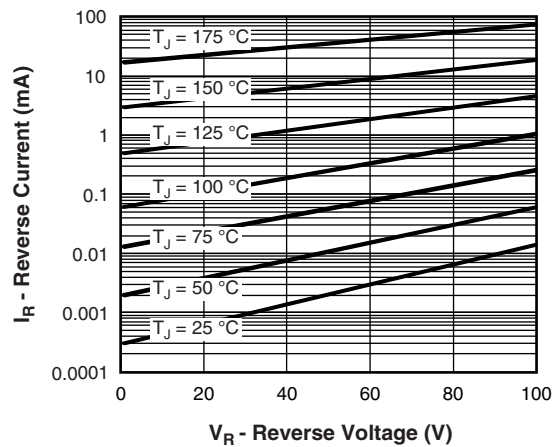


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

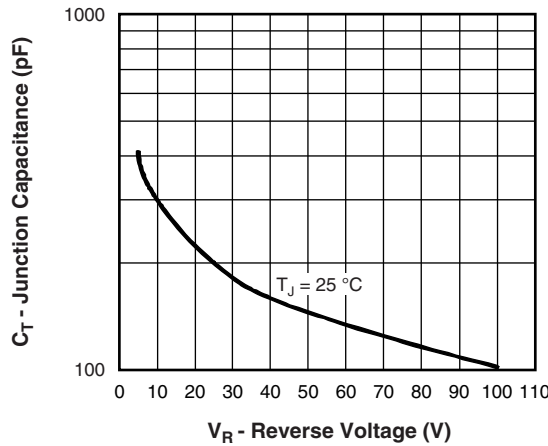


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

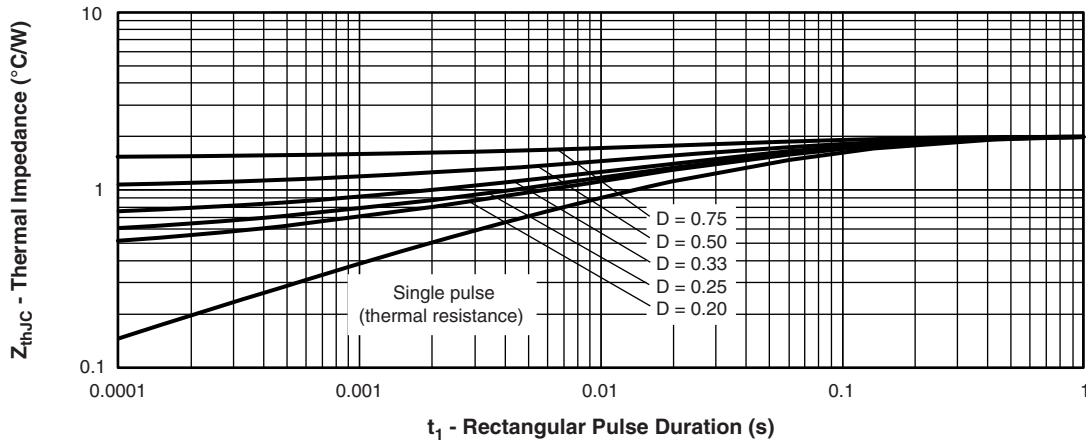


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

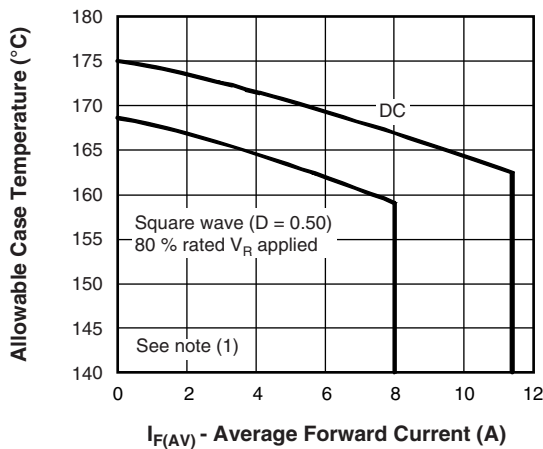


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

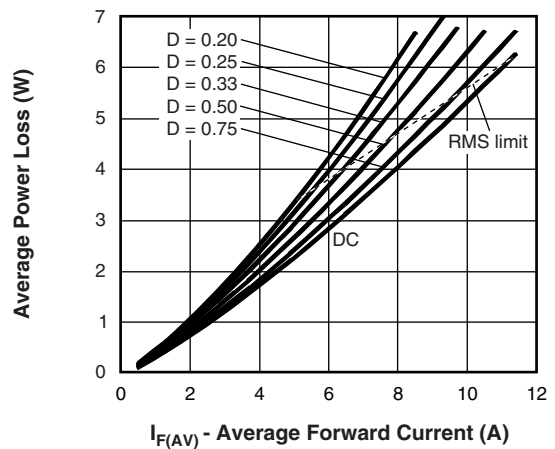


Fig. 6 - Forward Power Loss Characteristics

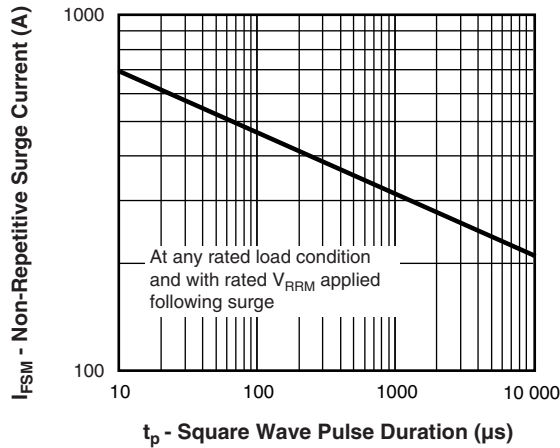


Fig. 7 - Maximum Non-Repetitive Surge Current

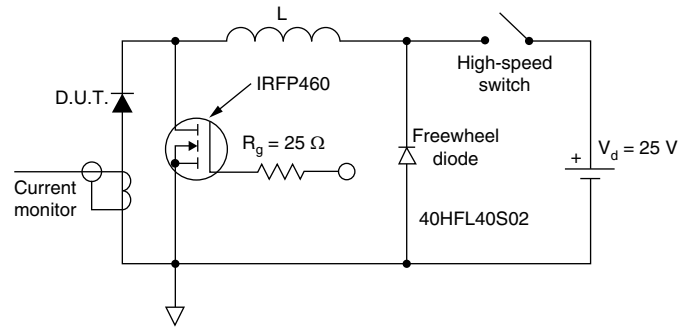


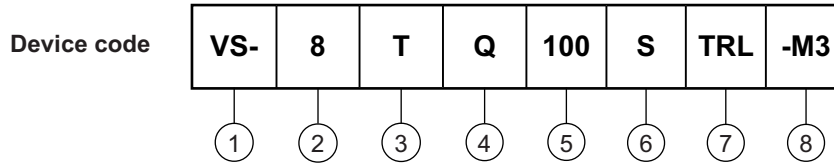
Fig. 8 - Unclamped Inductive Test Circuit

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
- P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
- $P_{d_{REV}}$ = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (8 A)
- 3** - Circuit configuration: T = TO-220
- 4** - Schottky "Q" series
- 5** - Voltage ratings 080 = 80 V
100 = 100 V
- 6** - S = D²PAK (TO-263AB)
- 7** -
 - None = tube
 - TRL = tape and reel (left oriented)
 - TRR = tape and reel (right oriented)
- 8** - -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-8TQ080S-M3	50	Antistatic plastic tubes
VS-8TQ080STRL-M3	800	13" diameter plastic tape and reel
VS-8TQ080STRR-M3	800	13" diameter plastic tape and reel
VS-8TQ100S-M3	50	Antistatic plastic tubes
VS-8TQ100STRL-M3	800	13" diameter plastic tape and reel
VS-8TQ100STRR-M3	800	13" diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96164
Part marking information	www.vishay.com/doc?95444
Packaging information	www.vishay.com/doc?96424
SPICE model	www.vishay.com/doc?96227

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190		D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010		E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039		E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4	e	2.54 BSC		0.100 BSC		
b2	1.14	1.78	0.045	0.070		H	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4	L	1.78	2.79	0.070	0.110	
c	0.38	0.74	0.015	0.029		L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4	L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065		L3	0.25 BSC		0.010 BSC		
D	8.51	9.65	0.335	0.380	2	L4	4.78	5.28	0.188	0.208	

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB



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